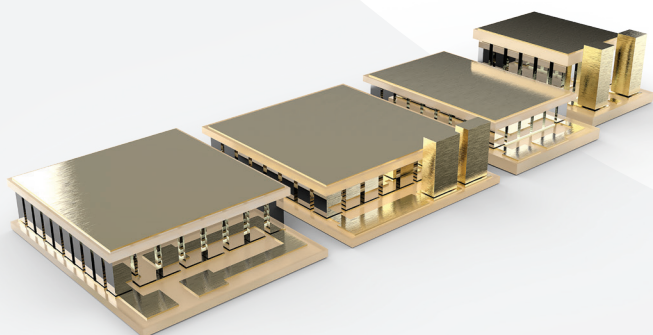


Technical Data sheet

TECs for Box TOSAs

Phononic's high-performance TEC solutions for box TOSA (transmit optical subassembly) laser packages deliver excellent cooling for applications of 100G or higher. They work well in QSFP transceiver packages, and are perfectly suited for cooled long reach requirements that are in demand from the growth of co-located and regional data centers. Customers are also working with us on their single-wavelength 100G+ applications. With inside-the-package differentiation and options supporting up to 1.6T, our TEC series will meet the needs of your box TOSA laser package regardless of factors like speed or distance. Leverage our expertise to plan your future product road map. We will not limit you to standard products; our solutions can be specifically designed and optimized to your needs.

Excellent for Long-Reach and High-Speed Applications



Features

- Lower power consumption
- Higher heat pumping density
- Supports 100G-1.6T applications
- Suited for long reaches
- Compatible with I-temp or C-temp ranges
- Application-specific designs available

End-Customer Applications

- CFPx MSA transceivers
- OSFP, QSFP28 and QSFP-DD (Quad Small Form Factor Pluggable) transceivers
- 100G DR1/LR1/LR4 TOSAs
- 400G DR4/FR4/LR4 and 800G DR4/DR8/FR8 TOSAs
- 100G/400G/800G Coherent
- High data rate LAN-WDM and DWDM (dense wavelength division multiplexing)
- I-Temp QSFP28 TOSAs for wireless front haul applications

Integration Options

- Bare wire bond pads
- Wire bonding posts
- Cold side electrical connections
- High-temperature solder
- Solder pre-tinning
- Patterned cold-side metalization
- Pre-attached cold-side thermistor
- Automation-ready packaging

Benefits

- **Extremely Low Power Consumption:** Achieve 30% lower power consumption than typical TEC performance
- **High Heat Pumping Density:** Realize up to 60% higher heat pumping density in a very thin TEC - our pico-TEC platform is perfect for data center and telecom applications
- **Exceptional Design Support:** Benefit from our expertise—we'll consult with you, enabling faster time to market with a design done right the first time

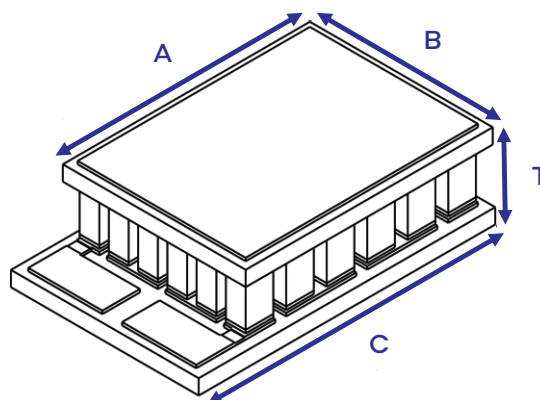
Product Portfolio

Part Number	TEC Dimensions				TEC Performance (Thot = 75°C)					AC Resistance @ 25°C (Ω)
	A [mm]	B [mm]	C [mm]	T [mm]	Optimal Heat Load [milliwatts]	Qc Max [Watts]	DT Max [°C]	V Max [Volts]	I Max [Amps]	
FBM-017990	8.50	2.70	9.30	0.93	590 - 1950	5.9	88	5.28	1.99	2.08
FBP-009364	3.90	4.20	4.90	0.66	580 - 1900	5.8	86	10.84	0.97	9.19
FBM-016859	4.10	4.10	4.90	1.00	500 - 1650	5.0	89	5.28	1.69	2.46
FBM-016140	4.20	2.90	4.90	1.00	420 - 1400	4.2	89	4.46	1.68	2.10
FBM-016936	4.20	4.50	5.00	0.85	290 - 960	2.9	89	3.97	1.31	2.58
FBM-016916	2.80	2.70	3.50	1.30	240 - 800	2.4	89	3.46	1.23	2.22
FBM-017066	4.10	2.20	4.85	0.93	180 - 600	1.8	89	3.64	0.90	3.19
FBB-017256	3.00	4.20	3.80	1.60	130 - 430	1.3	93	2.65	0.85	2.65
FBM-017996	6.45	2.70	7.10	0.93	600 - 2000	6.1	88	3.95	2.74	1.13

*Optimal heat load is the cold side heat load range under which the TEC operates at or near highest efficiency conditions. Hot side temperature is 75°C, cold side temperature is 45°C to 55°C.

Application Considerations

For maximum reliability, TEC storage and operation at or below 85°C ambient in a non-condensing environment is recommended. Recommended mounting methods are bonding with thermal epoxy or soldering with metalized ceramics. For additional information or assistance selecting the right TEC for your application, please consult with one of our Applications Engineers at **1.844.476.4202** or at www.phononic.com/contact/



Learn More:

